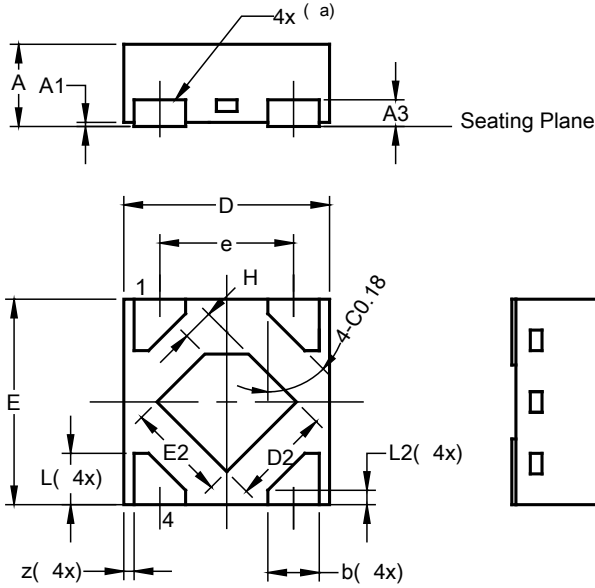


Package Outline Dimensions

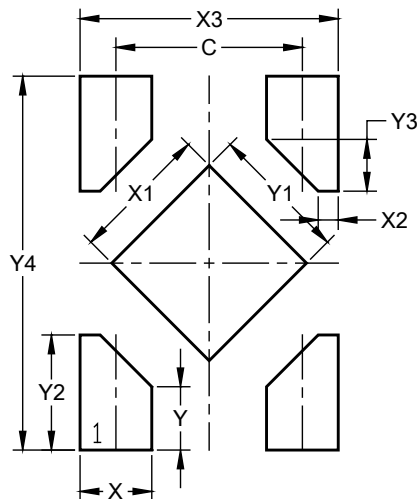
X1-DFN1010-4 (Type C)



X1-DFN1010-4 (Type C)			
Dim	Min	Max	Typ
A	0.37	0.43	0.39
A1	0.00	0.05	0.02
A3	--	--	0.13
b	0.20	0.30	0.25
D	0.95	1.05	1.00
D2	0.43	0.53	0.48
E	0.95	1.05	1.00
E2	0.43	0.53	0.48
e	--	--	0.65
H	--	--	0.150
L	0.20	0.30	0.25
L2	0.02	0.12	0.07
z	--	--	0.050
All Dimensions in mm			

Suggested Pad Layout

X1-DFN1010-4 (Type C)



Dimensions	Value (in mm)
C	0.650
X	0.250
X1	0.480
X2	0.070
X3	0.900
Y	0.220
Y1	0.480
Y2	0.400
Y3	0.180
Y4	1.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.